

## REMARKS

This Amendment is fully responsive to the final Office Action dated September 22, 2008, issued in connection with the above-identified application. Claims 1-11 are pending in the present application. With this Amendment, claims 1, 3, 4, 8 and 10 have been amended. No new matter has been introduced by the amendments made to the claims. Favorable reconsideration is respectfully requested.

In the Office Action, claims 1-4, 7, 8 and 10 have been rejected under 35 U.S.C. 103(a) as being unpatentable over Yasue et al. (U.S. Patent No. 6,010,768, hereafter “Yasue”) in view of the Applicant’s Admitted Prior Art (hereafter “the AAPA”). The Applicant has herein amended independent claim 1 to help further distinguish the present invention from the cited prior art.

Specifically, as amended, independent claim 1 now more particularly points out that the method of manufacturing a printed wiring board includes the use of a metallic foil with a roughened surface facing the resin layer that is superposed on the resin layer. This feature of independent claim 1 (as amended) is fully supported by the Applicant’s disclosure (see e.g., ¶¶15 and 16).

The present invention, as recited in claim 1, is directed to a method of manufacturing a printed wiring board that includes the use of a metallic foil with a roughened surface that faces the resin layer and that is superposed on the resin layer. The metallic foil with the roughened surface facilitates the spreading of the resin. Additionally, the metallic foil also forms a surface of the resin layer in a fine uneven state in accordance with the roughened surface of the metallic foil. As a result, the residual resin layer can be more easily polished. Additionally, in the case where the metallic foil is formed on a different type of metal from the circuit patterns, it is possible to remove the metallic foil by selective etching or dissolving only the metallic foil without affecting the circuit patterns.

In the Office Action, the Examiner correctly notes that neither Yasue nor the AAPA disclose or suggest the use of a metallic foil having a roughened surface facing the resin layer (see e.g., Office Action on pg. 3). However, the Examiner also indicates that it would have been an obvious matter of design choice to use a metallic foil with a roughened surface pressed against

the resin layer because the Applicant has not disclosed that using such a metallic foil would provide an advantage, is used or a particular purpose, or solves a stated problem.

However, the Applicant respectfully points out that the Applicant's disclosure clearly states the advantages, the particular purpose, or problem solved by use of a metallic foil having a roughened surface facing the resin layer. As specifically stated in the Applicant's disclosure, when a smoothing plate is pressed against a resin layer located on the substrate, a metallic foil with a roughened surface faces the resin layer, wherein the metallic foil is disposed between the smoothing plate and the resin layer. In this configuration, the metallic foil facilitates the spreading of the resin.

Additionally, the metallic foil also forms the surface of the resin layer in a fine uneven state in accordance with a roughened surface of the metallic foil. Thus, the residual resin layer can be more easily polished.

Finally, in the case where the metallic foil is formed of a different type of metal from the circuit pattern, it is possible to remove the metallic foil by selective etching or dissolving only the metallic foil without affecting the metal of the circuit patterns (see e.g., ¶¶15-16).

As noted above, the Applicant's disclosure clearly states the advantages, the particular purpose, or problem solved by use of the metallic foil having a roughened surface, as recited in claim 1 (as amended). Additionally, neither Yasue nor the AAPA disclose or suggest the use of the metallic foil having a roughened surface, as recited in claim 1 (as amended).

Accordingly, no combination of Yasue and the AAPA would result in, or otherwise render obvious, the present invention as recited in independent claim 1 (as amended). Likewise, no combination of Yasue and the AAPA would result in, or otherwise render obvious, claims 3, 4, 7, 8 and 10 at least by virtue of their dependency from independent claim 1.

In the Office Action, claims 5, 6, 9 and 11 have been rejected under 35 U.S.C. 103(a) as being unpatentable over Yasue in view of the AAPA, and further in view Fukutomi et al. (U.S. Patent No. 6,268,648, hereafter "Fukutomi").

Claims 5, 6, 9 and 11 depend from independent claim 1. As noted above, Yasue and the AAPA fail to disclose or suggest all the features recited in independent claim 1 (as amended).

Additionally, after a detailed review of Fukutomi, the reference fails to overcome the deficiencies noted above in Yasue and the AAPA. Therefore, no combination of Yasue, the AAPA and Fukutomi would result in, or otherwise render obvious, claims 5, 6, 9 and 11 at least by virtue of their dependency from independent claim 1.

In light of the above, the Applicant respectfully submits that all the pending claims are patentable over the prior art of record. The Applicant respectfully requests that the Examiner withdraw the rejections presented in the outstanding Office Action, and pass the application to issue. The Examiner is invited to contact the undersigned attorney by telephone to resolve any remaining issues.

Respectfully submitted,

Keiichi MURAKAMI

By:



Mark D. Pratt

Registration No. 45,794  
Attorney for Applicant

MDP/ats  
Washington, D.C. 20006-1021  
Telephone (202) 721-8200  
Facsimile (202) 721-8250  
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